

Features

- PLCC-6 package.
- White package.
- Optical indicator.
- Colorless clear window.
- Ideal for backlight and light pipe application.
- Wide viewing angle.
- Suitable for automatic placement equipment.
- The product itself will remain within RoHS compliant Version.

RS PRO LEDs

RS Stock No.: 0588778



RS PRO is the own brand of RS. The RS PRO Seal of Approval is your assurance of professional quality, a guarantee that every part is rigorously tested, inspected, and audited against demanding standards. Making RS PRO the Smart Choice for our customers.

Product Description

Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the SMT TOP LED ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

- Backlight in dashboards and switches.
- Telecommunication: Indicator and backlight in telephone and fax.
- Indicator and backlight for audio and video equipment.
- Indicator and backlight in office and family equipment.
- Flat backlight for LCD's, switches and symbols.
- Light pipe application.
- General use.

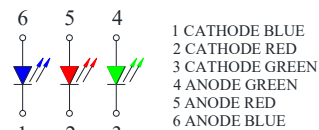
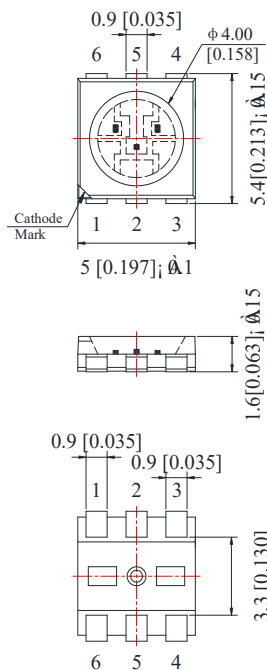
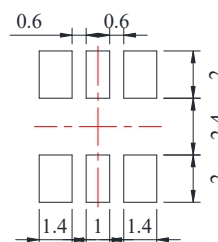
General Specifications

<i>LED Colour</i>	5050RGB, SMD LED
<i>Dimensions</i>	5.4x 5.0mm, Surface Mount Chip LED Indicator

Mechanical Specifications

Mechanical Life

Recommended Soldering Pad Dimensions
Soldering Temperature : 260°C for 5Seconds

**Polarity****Recommended Soldering Pad dimensions****Notes:**

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 mm (.010") unless otherwise noted.

Electrical Specifications

Absolute Maximum Ratings at $T_a=25^\circ\text{C}$

Parameters		Symbol	Max.	Unit
Power Dissipation	R	PD	60	mW
	G		85	
	B		85	
Peak Forward Current (Per Chip) ^(a)		IFP	100	mA
Forward Current (Per Chip) ^(b)	R	IF	25	mA
	G		25	
	B		25	
Reverse Voltage (Per Chip)		VR	5	V
Electrostatic Discharge (HBM)	R	ESD	2000	V
	G		1000	
	B		1000	
Operating Temperature Range		Topr	-40□ to +85□	
Storage Temperature Range		Tstg	-40□ to +85□	
Lead Soldering Temperature [4mm (.157□) From Body]		Tsld	250□ for 5 Seconds	

Notes:

- Duty Factor = 10%, Frequency = 1 kHz
- Derate linearly as shown in derating curve.

Electrical Optical Characteristics at Ta=25°C

Parameters	Symbol	Emitting Color	Min.	Typ.	Max.	Unit	Test Condition
------------	--------	----------------	------	------	------	------	----------------

Luminous Intensity ^(a)	IV	R	650	800	---	mcd	IF=20mA
		G	1500	2000	---		
		B	400	600	---		
Viewing Angle	2θ _{1/2}	R	---	120	---	Deg	IF=20mA
		G	---	120	---		
		B	---	120	---		
Peak Emission Wavelength	λ _p	R	---	632	---	nm	IF=20mA
		G	---	520	---		
		B	---	468	---		
Dominant Wavelength ^(b)	λ _d	R	---	624	---	nm	IF=20mA
		G	---	525	---		
		B	---	470	---		
Spectral Line Half-Width	Δλ	R	---	20	---	nm	IF=20mA
		G	---	35	---		
		B	---	25	---		
Forward Voltage ^(c)	VF	R	1.60	2.00	2.40	V	IF=20mA
		G	2.80	3.10	3.40		
		B	2.80	3.10	3.40		
Reverse Current	IR	R	---	---	10	μA	V _R =5V
		G					
		B					

Notes:

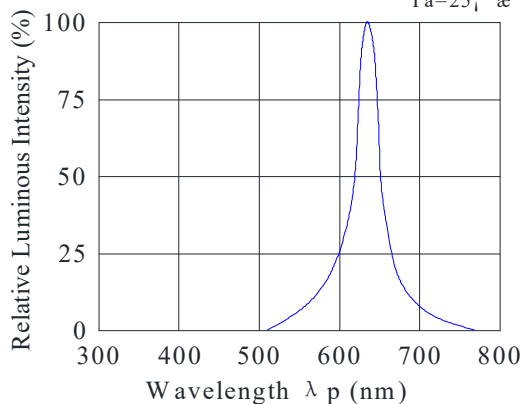
- a. Luminous flux measurement tolerance: ±10%.
- b. Color coordinates measurement tolerance: ±0.015
- c. Forward voltage measurement tolerance: ±0.1V

Typical Electrical / Optical Characteristics Curves

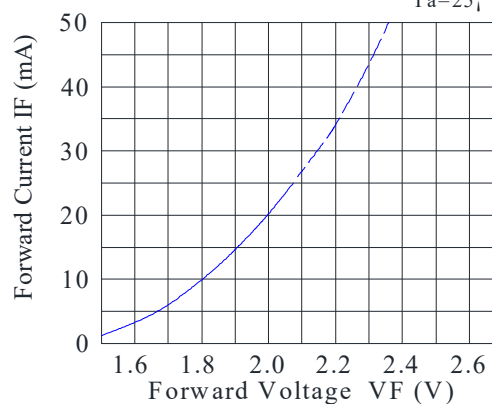
(25°C Ambient Temperature Unless Otherwise Noted)

Red

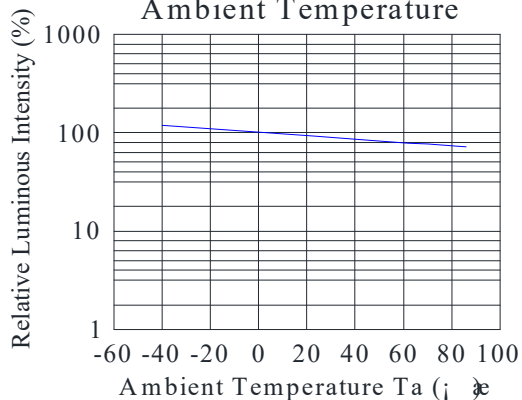
Spectrum Distribution

 $T_a = 25^\circ\text{C}$ 

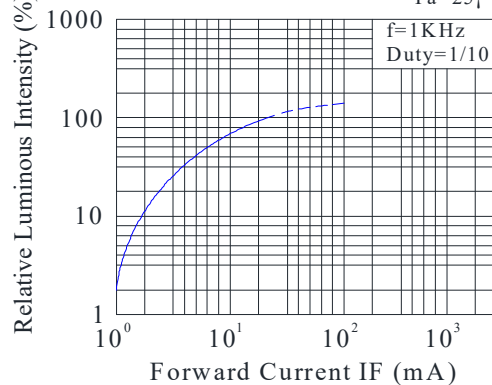
Forward Current & Forward Voltage

 $T_a = 25^\circ\text{C}$ 

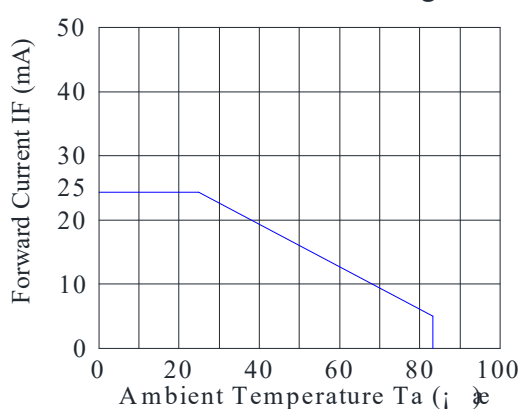
Luminous Intensity & Ambient Temperature



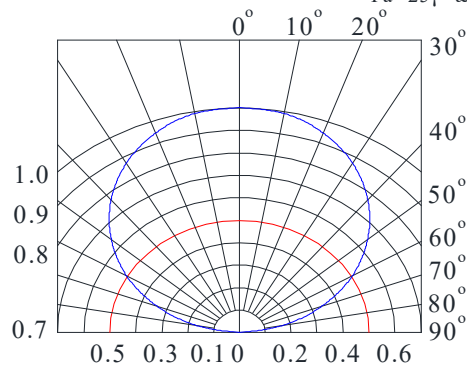
Luminous Intensity & Forward Current

 $T_a = 25^\circ\text{C}$ 

Forward Current Derating Curve



Radiation Diagram

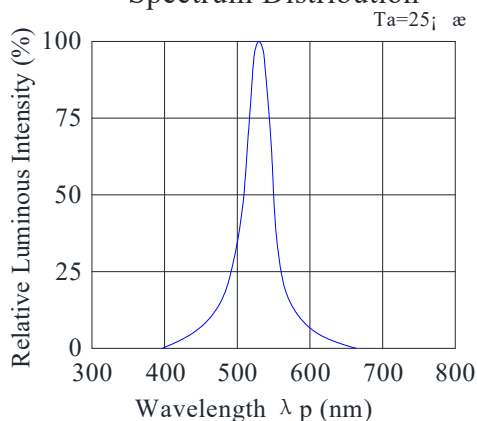
 $T_a = 25^\circ\text{C}$ 

Typical Electrical / Optical Characteristics Curves

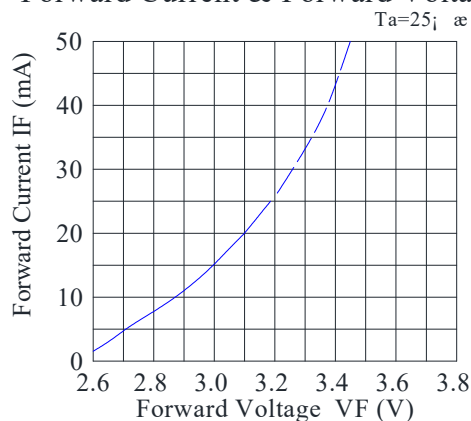
(25 $^\circ\text{C}$ Ambient Temperature Unless Otherwise Noted)

Green

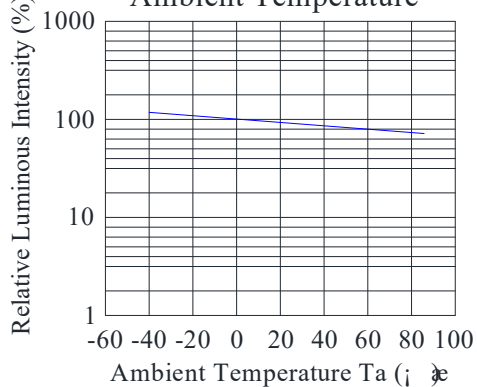
Spectrum Distribution



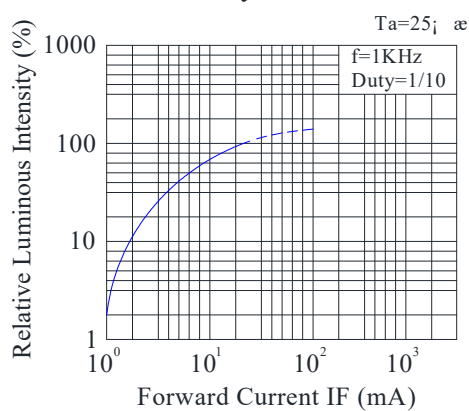
Forward Current & Forward Voltage



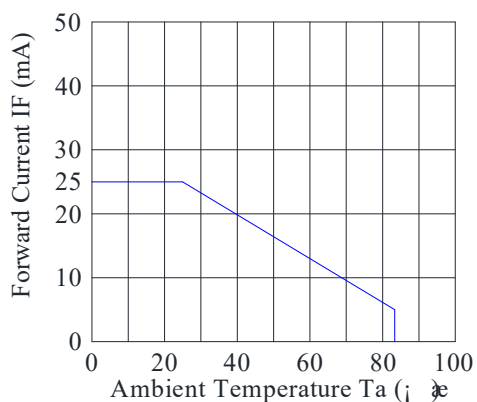
Luminous Intensity & Ambient Temperature



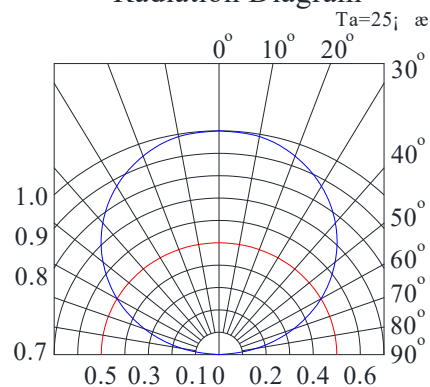
Luminous Intensity & Forward Current



Forward Current Derating Curve



Radiation Diagram

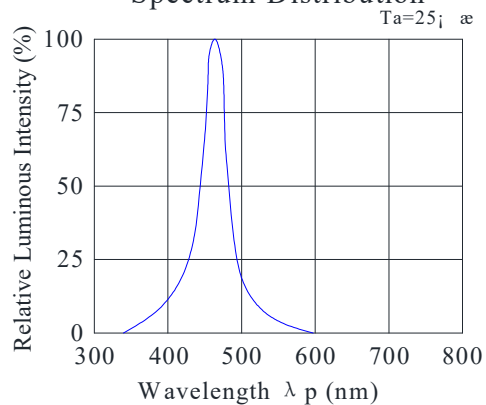


Typical Electrical / Optical Characteristics Curves

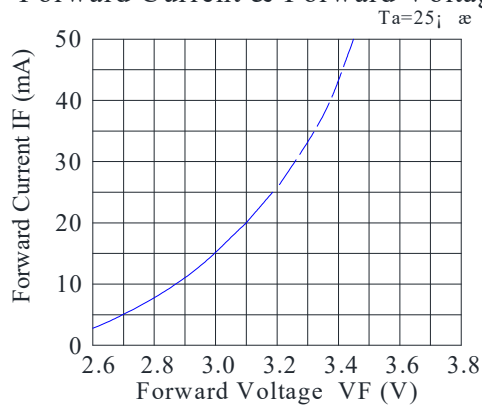
(25°C Ambient Temperature Unless Otherwise Noted)

Blue

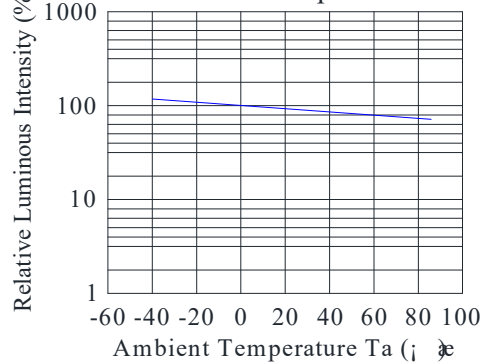
Spectrum Distribution



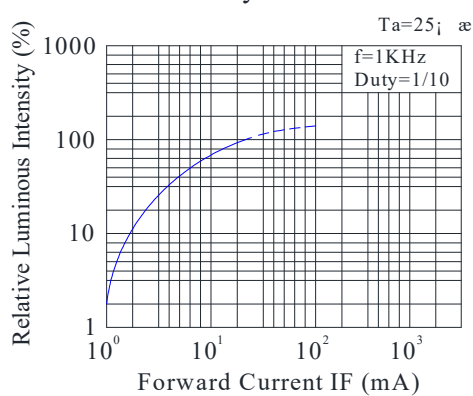
Forward Current & Forward Voltage



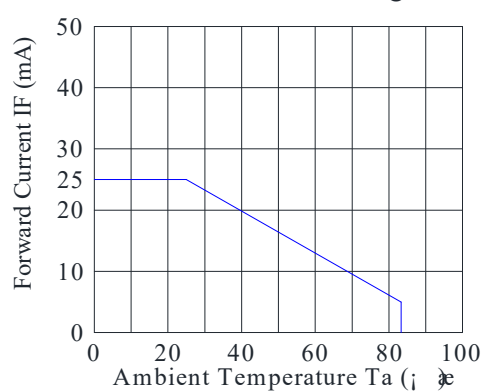
Luminous Intensity & Ambient Temperature



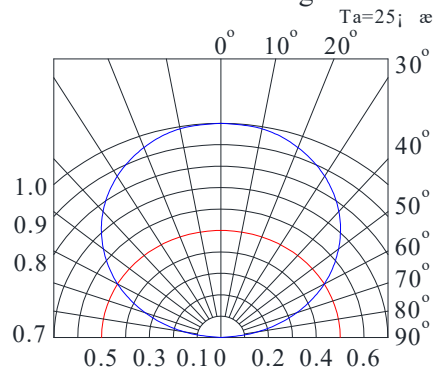
Luminous Intensity & Forward Current



Forward Current Derating Curve



Radiation Diagram



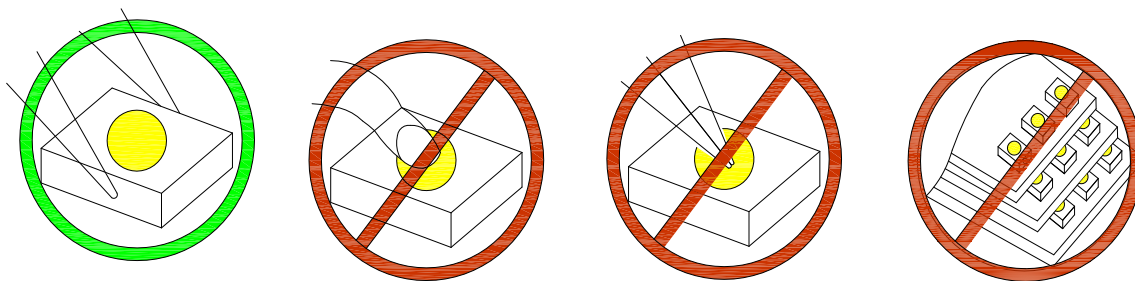
CAUTIONS

1. Handling Precautions:

1.1 Handle the component along the side surfaces by using forceps or appropriate tools.

1.2 Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

1.3 Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



1.4 compared to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

2. Storage:

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

2.3 The LEDs should be used within a year.

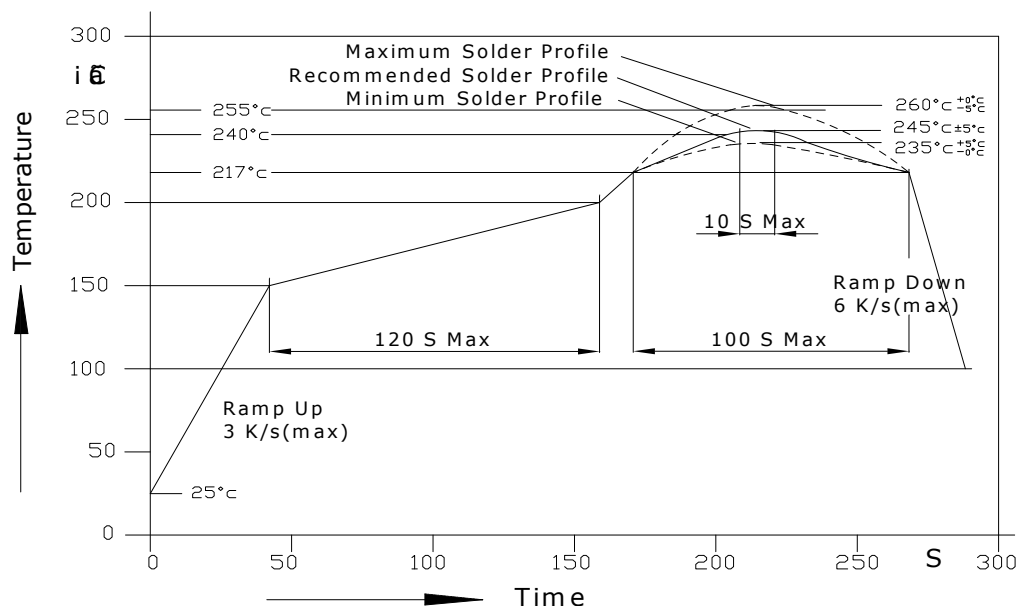
2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

2.5 The LEDs should be used within 24 hours after opening the package.

2.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 65±5°C for 24 hours.

3. Soldering Condition:

3.1 Pb-free solder temperature profile.



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

3.5 Recommended soldering conditions:

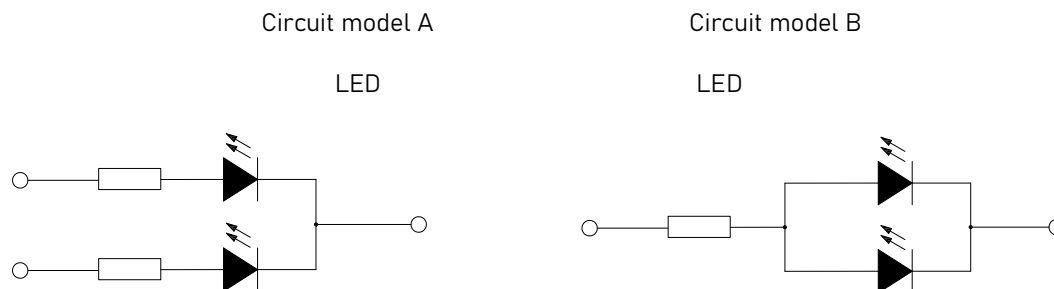
Reflow soldering		Soldering iron	
Pre-heat	150~200°C	Temperature	300°C Max.
Pre-heat time	120 sec. Max.	Soldering time	3 sec. Max.
Peak temperature	260°C Max.		(one time only)
Soldering time	10 sec. Max. (Max. two times)		

3.6 Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.

However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

4. Drive Method:

4.1 An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



(A) Recommended circuit.

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

5. ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded. □
- Work tables, storage racks, etc. should be properly grounded. □
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents. To verify for ESD damage, check for "lightup" and V_f of the suspect LEDs at low currents. The V_f of "good" LEDs should be $>2.0V@0.1mA$ for InGaN product and $>1.4V@0.1mA$ for AlInGaP product.

Terms and conditions for the usage of this document:

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, RS will not be responsible for any subsequent issues.
4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with RS representative for further assistance.

5. The contents and information of this document may not be reproduced or re-transmitted without permission by RS.